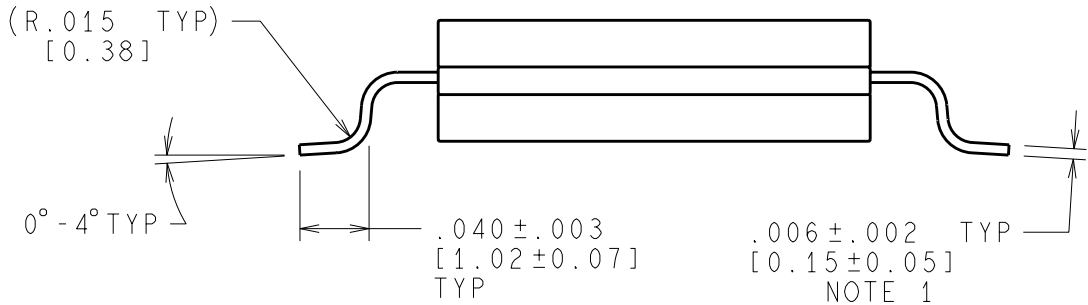
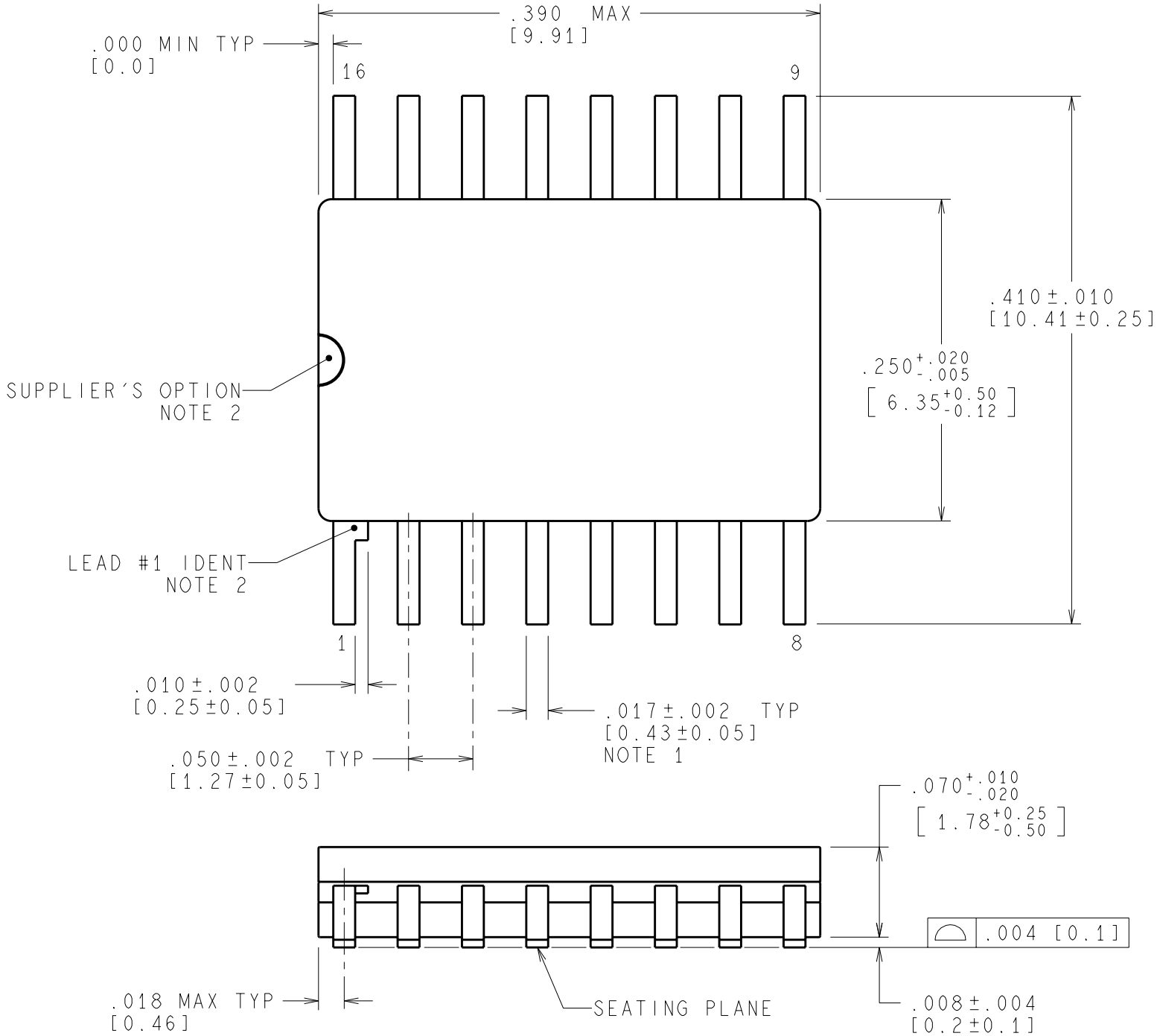


REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	11376	02/29/1996	MS/KH
B	LD PITCH TOL WAS $\pm .005$; CHANGE LD RADIUS TO REF DIM; REMOVE THE OTHER R.006 $\pm .002$; DIM .040 $\pm .003$ WAS .037 $\pm .003$	11443	04/19/1996	MS/KH
C	R .015[0.38] WAS R .006[0.15]	11840	10/08/1997	TL/KH
D	.000 MIN WAS .005 MIN; UPDATE TITLE; CHANGE TO B SIZE FORMAT	1535	07/13/2004	TL/CBS



NOTES: UNLESS OTHERWISE SPECIFIED

- LEAD FINISH: SOLDER DIPPED WITH Sn60 OR Sn63 SOLDER CONFORMING TO MIL-PRF-38535 TO A MINIMUM THICKNESS OF 200 MICROINCHES/ 5.08 MICROMETERS. SOLDER MAY BE APPLIED OVER LEAD BASE METAL OR Sn PLATE. MAXIMUM LIMIT MAY BE INCREASED BY .003 IN/ 0.08mm AFTER LEAD FINISH APPLIED.
- LEAD 1 IDENTIFICATION SHALL BE:
 - A NOTCH OR OTHER MARK WITHIN THIS AREA.
 - A TAB ON LEAD 1, EITHER SIDE.
- NO JEDEC REGISTRATION AS OF JULY 2004.

CONTROLLING DIMENSION IS INCH
VALUES IN [] ARE MILLIMETERS

MIL-PRF-38535
CONFIGURATION CONTROL

APPROVALS		DATE	National Semiconductor 2900 Semiconductor Dr., Santa Clara, CA 95052-8090	
DRAWN	MARTA SUCHY	02/29/1996		
DTG. CHK.	MARTA SUCHY	07/13/2004	CERPACK, .25x.39x.07in, 16 LD, .05in PITCH, GULL WING	
ENGR. CHK.	ALVIN CB SIM	07/13/2004		
PROJECTION		DATE	SCALE	SIZE
		DATE	NTS	B
INCH (MM)		DATE	FORMERLY: N/A	DRAWING NUMBER
		DATE		(SC)MKT-WG16A
		DATE		REV
		DATE		D
		DATE		SHEET 1 of 1